



PRESS RELEASE

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TechSearch International Examines Chiplet Strategies and Markets, North American OSAT Capability, and Provides an Update on the Build-up Substrate Supply and Demand

TechSearch International's latest analysis examines strategies for the adoption of chiplets and current products. While the market is small today in unit volume, a 103% CAGR is projected from 2022 to 2026. Challenges, including design and test, are discussed.

The report includes OSAT financials and examines economic trends impacting the industry. The North American OSAT market is examined with a focus on advanced packaging capability. Future plans for North American OSATs are discussed. The report also highlights packaging and assembly in Mexico.

TechSearch International analyzes the supply and demand for build-up substrates used for flip chip BGAs. The sharp decline in the PC and other markets have lowered demand and the industry has excess capacity. Some unused capacity is being released this year and a few substrate makers are slowing capacity expansion. Substrate companies are facing price pressure, creating an unhealthy condition for the industry.

The latest Advanced Packaging Update is a 47-page report with full references and an accompanying set of more than 40 PowerPoint slides.

TechSearch International, Inc., founded in 1987, is a market research leader specializing in technology trends in microelectronics packaging and assembly. Multi- and single-client services encompass technology licensing, strategic planning, and market and technology analysis. TechSearch International professionals have an extensive network of more than 22,000 contacts in North America, Asia, and Europe. For more information, contact TechSearch at tel: 512-372-8887 or see www.techsearchinc.com. Follow us on LinkedIn.